ASCOLUTION CONNECTING ELECTRONICS INDUSTRIES international and Pa	Dosition De IPC, Bannock In-American c	eclaration burn, Illinois. A copyright conver	ll rights reserved untions.	under both									te: if the item turer has engin		
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplier Information															
Company name* Company unique ID			ique ID		Unique ID Authority						Response Date*				
nsemi						2025-07-15									
ontact Name	Title - Conta	- Contact			Phone - Contact*				Email -	Email - Contact*					
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product	Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Represen			sentative	Phone - Representative* Email				Email -	nail - Representative*						
roduct-Env-Stewards	Product Enviro Compliance				NA				Product	Product-Env-Stewards@onsemi.com					
Requester Item Number	Requester Item Number Mfr Iter		n Number Mfr Item Name			Effective Date Version Manufacturing Site		cturing Site	V	Weight*	* UON	1	Unit Type		
	MT9M0 DRBR	T9M034I12STM- I.2 MP 1/3 CIS				2025-07-15	5 TA1		2	240.0	mg		Each		
Ianufacturing Proccess Informa	ation						·				·		·		
Terminal Plating / Grid Array M	/ Grid Array Material Terminal Base Alloy		Alloy	J-STD-020 MS	ASL Rating Pea		ak Process Body Temperature Max Time at Pea		ak Temperat	x Temperature Number of Reflow Cycles					
Precious metal (e.g. Ag,Au, NiPdAu) (no Cu Sn)		CU Alloy	Alloy 4			260 C		С	30 sec		secon	ds 3			
omments															
or more information regarding materia	l compositior	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed								
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	IS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl malate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of								
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.													
Exemption List Version	EL-2011/534/EU												
Declaration Signature													
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the								
Supplier Digital Signature Ra	stislav Drska	Le											

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	50.57	mg		Misc.	proprietary data		0.1922	mg
			Supplier	Silicon (Si)	7440-21-3		49.8772	mg
			Supplier	Aluminum (Al)	7429-90-5		0.5006	mg
Die Attach	1.78	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.6675	mg
			Supplier	Ethylene Glycol	107-21-1		0.0178	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0534	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.3738	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.6675	mg
Imaging Lens	50.18	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.509	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.509	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.509	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.509	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2509	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.509	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.509	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		34.8751	mg
Lid Attach	2.35	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		1.0575	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.47	mg
			Supplier	Filler (SiO2)	68909-20-6		0.2937	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.0117	mg
			Supplier	Curative	Proprietary Data		0.047	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.47	mg
Mold Compound-Black	53.81	mg		Phenolic Resin	proprietary data		8.0715	mg
			Supplier	Oxirane	39817-09-9		8.0715	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.6143	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5381	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.4384	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.0762	mg
Substrate and Solder Mask	81.05	mg	Supplier	Acetophenone	98-86-2		1.5886	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		17.985	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.0618	mg

			Supplier	Silica Amorphous (SiO2)	7631-86-9	1.0699	mg
			Supplier	Carbon Black (C)	1333-86-4	0.2675	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2675	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.1772	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	8.105	mg
			Supplier	Copper (Cu)	7440-50-8	39.3093	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.2185	mg
Wire Bond - Au	0.26	mg	Supplier	Gold (Au)	7440-57-5	0.26	mg